



Material Composition Declaration

EPC2007C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	3.4 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.9085	86.69	88.89	866923
	Silicon oxide	7631-86-9	0.0110	0.33		3284
	Silicon nitride	12033-89-5	0.0033	0.10		989
	Gallium nitride	25617-97-4	0.0142	0.42		4242
	Aluminum	7429-90-5	0.0214	0.64		6384
	Aluminum nitride	24304-00-5	0.0033	0.10		984
	Titanium	7440-32-6	0.0005	0.01		142
	Titanium nitride	25583-20-4	0.0027	0.08		790
	Copper	7440-50-8	0.0007	0.02		212
	Tungsten	7440-33-7	0.0006	0.02		166
	Polyimide		0.0161	0.48		4793
Under Bump Metal	Titanium	7440-32-6	0.0005	0.02	1.32	157
	Nickel	7440-02-0	0.0156	0.46		4648
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0282	0.84		8415
Solder Bump	Tin	7440-31-5	0.3201	9.54	9.79	95423
	Silver	7440-22-4	0.0082	0.24		2447
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			3.4	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.